

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
18 October 2001 (18.10.2001)

PCT

(10) International Publication Number
WO 01/77243 A1

(51) International Patent Classification⁷: C09J 4/06, C08F 290/04, 290/12, C09J 4/00, C08F 2/44, H01L 21/52

(21) International Application Number: PCT/JP01/03040

(22) International Filing Date: 9 April 2001 (09.04.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2000-107637 10 April 2000 (10.04.2000) JP
2000-257734 20 August 2000 (20.08.2000) JP
2000-281109 18 September 2000 (18.09.2000) JP
2000-296899 28 September 2000 (28.09.2000) JP
2000-306227 5 October 2000 (05.10.2000) JP

Shinagawa-ku, Tokyo 140-0002 (JP). **MURAYAMA, Ryuichi** [JP/JP]; c/o Sumitomo Bakelite Company Limited, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **ONAMI, Kazuhito** [JP/JP]; c/o Sumitomo Bakelite Company Limited, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **KAGIMOTO, Tomohiro** [JP/JP]; c/o Sumitomo Bakelite Company Limited, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP).

(74) Agents: **ASAMURA, Kiyoshi** et al.; Room 331, New Ohtemachi Bldg., 2-1, Ohtemachi 2-chome, Chiyoda-ku, Tokyo 100-0004 (JP).

(81) Designated States (*national*): CN, KR, SG, US.

(84) Designated States (*regional*): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR).

(71) Applicant (*for all designated States except US*): **SUMITOMO BAKELITE COMPANY LIMITED** [JP/JP]; 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP).

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **TANAKA, Nobuki** [JP/JP]; c/o Sumitomo Bakelite Company Limited, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **OKUBO, Hikaru** [JP/JP]; c/o Sumitomo Bakelite Company Limited, 5-8, Higashishinagawa 2-chome,

Published:

- with international search report
- with amended claims and statement

Date of publication of the amended claims and statement:

13 December 2001

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: DIE-ATTACHING PASTE AND SEMICONDUCTOR DEVICE

(57) Abstract: The present invention provides a die-attaching paste superior in solder cracking resistance, used for bonding of semiconductor chips. The present invention lies in a die-attaching paste comprising as essential components: (A) a hydrocarbon having a number-average molecular weight of 500 to 5,000 and at least one double bond in the molecule, or its derivative, (B) a reactive diluent, (C) a radical polymerization catalyst, and (D) a filler.

WO 01/77243 A1